



DMP6050SFG

60V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
	$50m\Omega @ V_{GS} = -10V$	-4.8A
-60V	70mΩ @ V _{GS} = -4.5V	-4.1A

Description and Applications

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

POWERDI®3333-8

- Backlighting
- **Power Management Functions**
- **DC-DC Converters**

Features and Benefits

- Low R_{DS(ON)} Ensures On State Losses Are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher **Density End Products**
- Occupies Just 33% of The Board Area Occupied by SO-8 Enabling Smaller End Product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

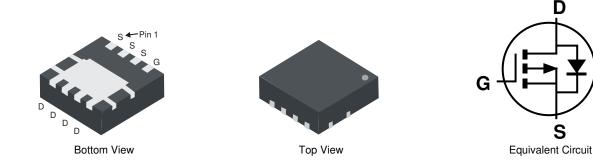
Mechanical Data

- Case: POWERDI[®]3333-8 •
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3

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Weight: 0.072 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP6050SFG-7	POWERDI [®] 3333-8	2000/Tape & Reel
DMP6050SFG-13	POWERDI [®] 3333-8	3000/Tape & Reel

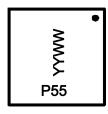
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes:

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http: //www.diodes.com/products/packages.html.

Marking Information



P55= Product Type Marking Code YYWW = Date Code Marking YY = Last Digit of Year (ex: 14 = 2014) WW = Week Code (01 to 53)

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Maximum Ratings @T_A = +25°C, unless otherwise specified.

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	-60	V		
Gate-Source Voltage			V _{GSS}	±20	V
Operation using Duration Operator (Nactor O) V (00000000000000000000000000000000000	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-4.8 -3.9	А
Continuous Drain Current (Note 6) $V_{GS} = -10V$	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-6.0 -4.8	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	-32	А		
Maximum Continuous Body Diode Forward Current (Note 6)			Is	-2.8	А
Avalanche Current (Note 7) L = 0.1mH			IAS	-24.8	А
Repetitive Avalanche Energy (Note 7) L = 0.1mH			E _{AS}	30.8	mJ

Thermal Characteristics @T_A = +25°C, unless otherwise specified.

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	1.1	W
Thermal Desistance, Junction to Ambient (Note 5)	Steady state	P	118	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	$R_{ extsf{ heta}JA}$	78	
Total Power Dissipation (Note 6)		PD	1.8	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	D	71	°C/W
Thermal Resistance, Junction to Amblent (Note 6)	t<10s	$R_{\theta JA}$	46	
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	6.7		
Operating and Storage Temperature Range		TJ. TSTG	-55 to +150	°C

Electrical Characteristics @T_A = +25°C, unless otherwise specified.

				-	-		
Characteristic	Symbol	Min	Тур	Мах	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-60	—	_	V	$V_{GS} = 0V, I_D = -250 \mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1	μA	$V_{DS} = -60V, V_{GS} = 0V$	
Gate-Source Leakage	Igss	—	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-1.0	_	-3.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Static Drain-Source On-Resistance		_	36	50	mΩ	$V_{GS} = -10V, I_D = -5A$	
Static Drain-Source On-Resistance	R _{DS (ON)}	—	47	70	11122	$V_{GS} = -4.5V, I_D = -4A$	
Diode Forward Voltage	V _{SD}	—	-0.7	-1.2	V	$V_{GS} = 0V, I_S = -1A$	
DYNAMIC CHARACTERISTICS (Note 9)	_					-	
Input Capacitance	Ciss	_	1293	_	pF	N 2014 N 014	
Output Capacitance	Coss	_	86.3	—	pF	−V _{DS} = -30V, V _{GS} = 0V, −f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	—	64.7		рF	1 - 1.00012	
Gate Resistance	Rg	—	12		Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = -4.5V)	Qg	—	11.9		nC		
Total Gate Charge (V _{GS} = -10V)		_	24		nC		
Gate-Source Charge	Qgs	_	3.6	—	nC	$V_{DS} = -30V, I_D = -5A$	
Gate-Drain Charge	Q _{gd}	_	5.7		nC	1	
Turn-On Delay Time	t _{D(ON)}	_	4.3	—	ns		
Turn-On Rise Time	t _R	_	6.3	—	ns	$V_{GS} = -10V, V_{DS} = -30V,$	
Turn-Off Delay Time	tD(OFF)		46.7		ns	$R_G = 3\Omega, I_D = -5A$	
Turn-Off Fall Time	tF	_	25.3	_	ns]	
Body Diode Reverse Recovery Time	t _{RR}	_	13.6	_	ns	I _F = -5A, di/dt = 100A/µs	
Body Diode Reverse Recovery Charge	Q _{RR}	_	7.4	—	nC	I _F = -5A, di/dt = 100A/μs	

Notes: 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

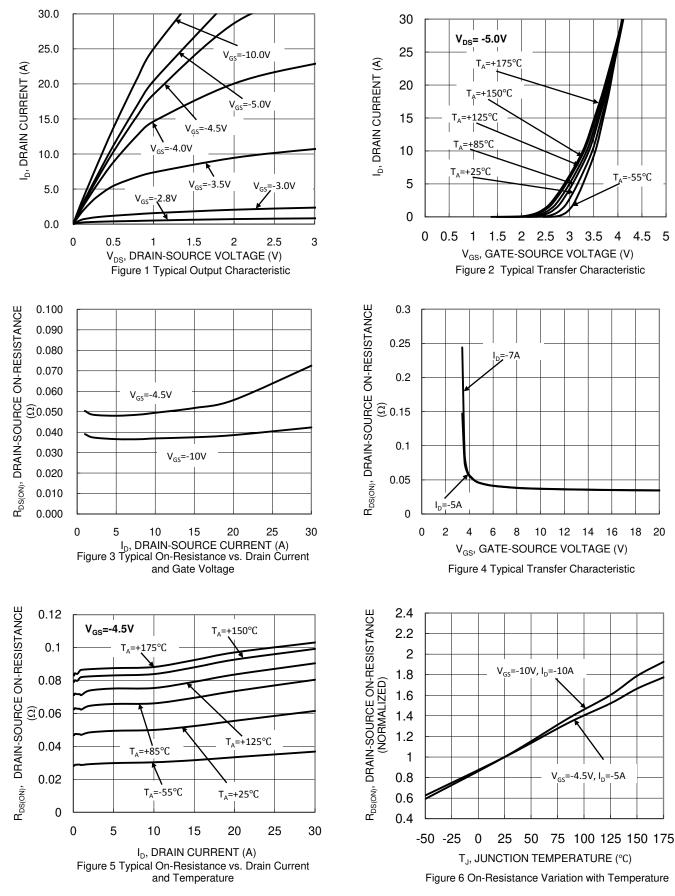
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1 inch square copper plate.

7. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_{J} = +25°C.

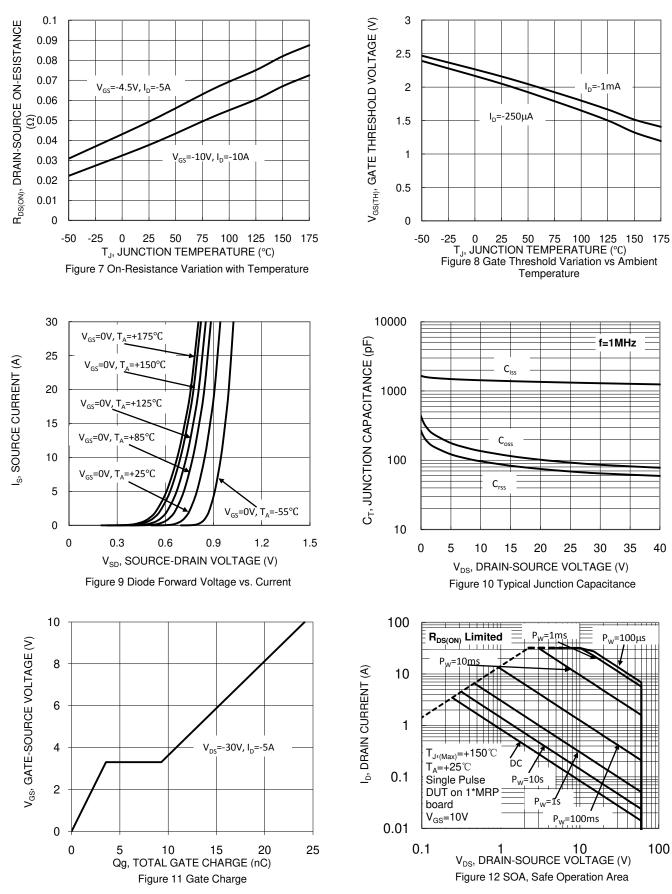
8. Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.





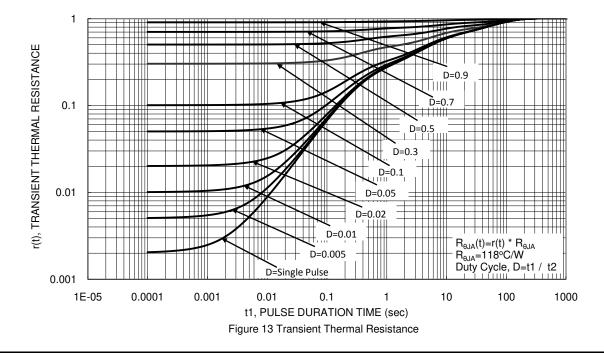




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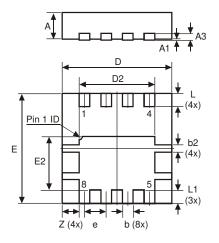
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Package Outline Dimensions

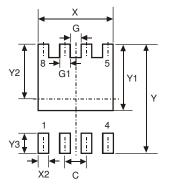
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



POWERDI [®] 3333-8					
Dim	Min	Min Max			
D	3.25	3.35	3.30		
Е	3.25	3.35	3.30		
D2	2.22	2.32	2.27		
E2	1.56	1.66	1.61		
Α	0.75	0.85	0.80		
A1	0	0.05	0.02		
A3	-	-	0.203		
b	0.27	0.37	0.32		
b2	-	-	0.20		
L	0.35	0.45	0.40		
L1	_	_	0.39		
е	-	_	0.65		
Z	_	_	0.515		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)				
С	0.650				
G	0.230				
G1	0.420				
Y	3.700				
Y1	2.250				
Y2	1.850				
Y3	0.700				
Х	2.370				
X2	0.420				



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